

Automotive Turbo 2 ultrafast high voltage rectifier

Features

- Ultrafast switching
- Low reverse recovery current
- Reduces switching losses
- Low thermal resistance
- AEC-Q101 qualified

Description

The STTH5R06, which uses ST Turbo 2 600 V technology, is specially suited as a boost diode in continuous mode power factor correction and hard switching conditions. This device is also intended for use as a free wheeling diode in power supplies and other power switching applications.

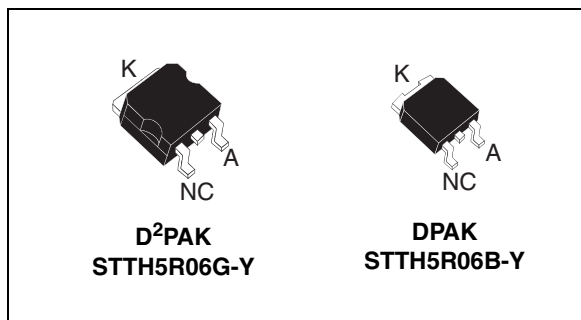


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	5 A
V_{RRM}	600 V
T_j	175 °C
V_F (typ)	1.5 V
t_{rr} (max)	35 ns

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter			Value	Unit	
V _{RRM}	Repetitive peak reverse voltage			600	V	
I _{F(RMS)}	Forward rms current	D ² PAK		25	A	
		DPAK		10		
I _{F(AV)}	Average forward current δ = 0.5	D ² PAK / DPAK	T _c = 145 °C	5	A	
I _{FSM}	Surge non repetitive forward current	T _p = 10 ms sinusoidal		D ² PAK	70	A
				DPAK	50	A
T _{stg}	Storage temperature range			-65 to + 175	°C	
T _j	Operating junction temperature range			-40 to + 175	°C	

Table 3. Thermal parameter

Symbol	Parameter	Maximum	Unit
$R_{th(j-c)}$	Junction to case	2.2	$^{\circ}\text{C/W}$

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ }^{\circ}\text{C}$	$V_R = V_{RRM}$			30	μA
		$T_j = 125\text{ }^{\circ}\text{C}$			30	300	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ }^{\circ}\text{C}$	$I_F = 5\text{ A}$			3.2	V
		$T_j = 125\text{ }^{\circ}\text{C}$			1.5	1.95	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation:

$$P = 1.35 \times I_{F(AV)} + 0.12 I_{F(RMS)}^2$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25\text{ }^{\circ}\text{C}$	$I_F = 0.5\text{ A}$, $I_{rr} = 0.25\text{ A}$, $I_R = 1\text{ A}$			20	ns
			$I_F = 1\text{ A}$, $di_F/dt = -50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$			35	
I_{RM}	Reverse recovery current	$T_j = 125\text{ }^{\circ}\text{C}$	$I_F = 5\text{ A}$, $di_F/dt = -200\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$		4.5	6	A
S_{factor}	Softness factor				0.5		-
Q_{rr}	Reverse recovery charges				110		nC
t_{fr}	Forward recovery time	$T_j = 25\text{ }^{\circ}\text{C}$	$I_F = 5\text{ A}$ $di_F/dt = 40\text{ A}/\mu\text{s}$ $V_{FR} = 2.5\text{ V}$			220	ns
V_{FP}	Forward recovery voltage					4.5	V

Figure 1. Average forward power dissipation versus average forward current

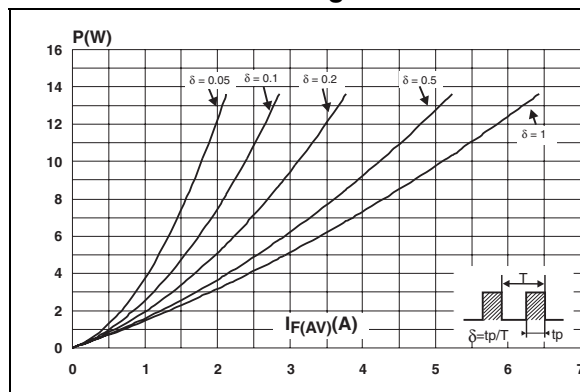


Figure 2. Forward voltage drop versus forward current

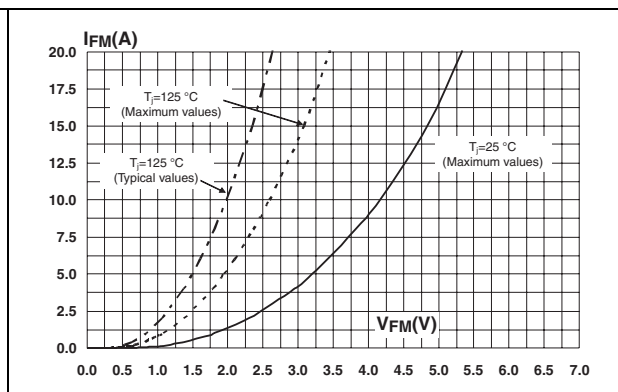


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

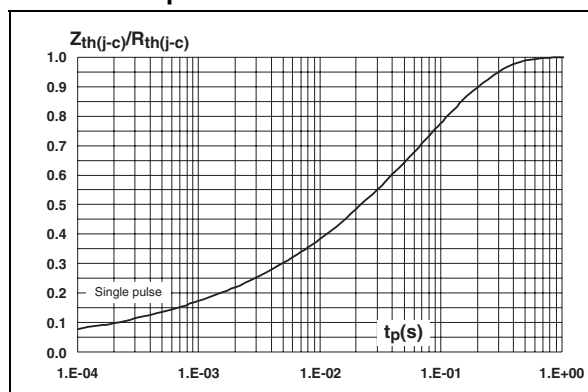


Figure 4. Peak reverse recovery current versus di_F/dt (typical values)

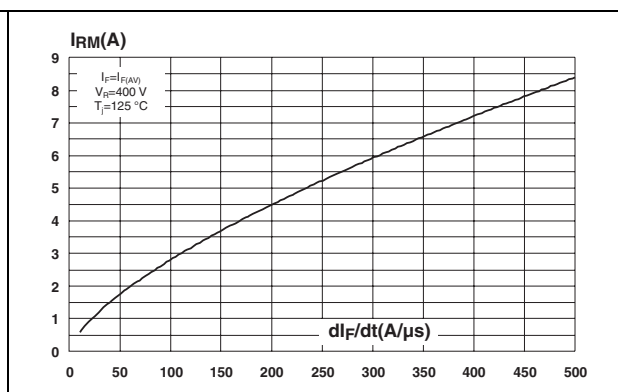


Figure 5. Reverse recovery time versus di_F/dt (typical values) **Figure 6. Reverse recovery charges versus di_F/dt (typical values)**

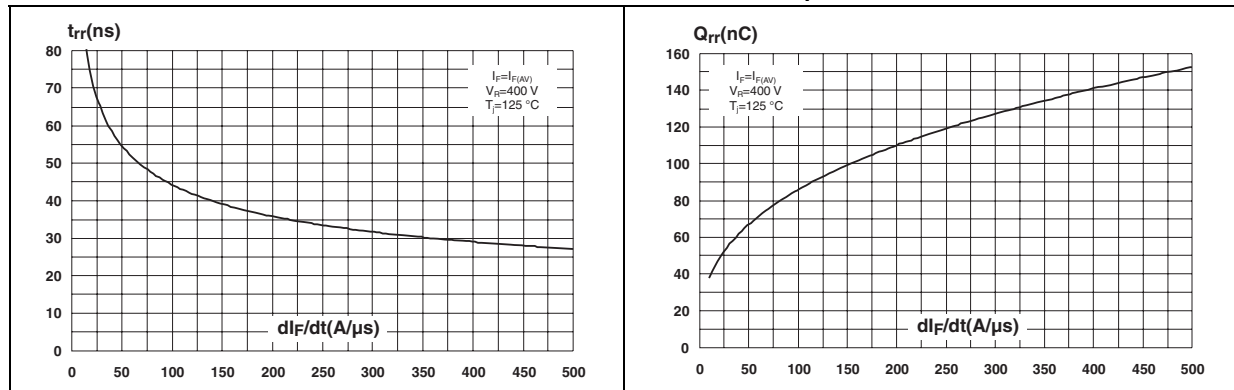


Figure 7. Softness factor versus di_F/dt (typical values) **Figure 8. Relative variations of dynamic parameters versus junction temperature**

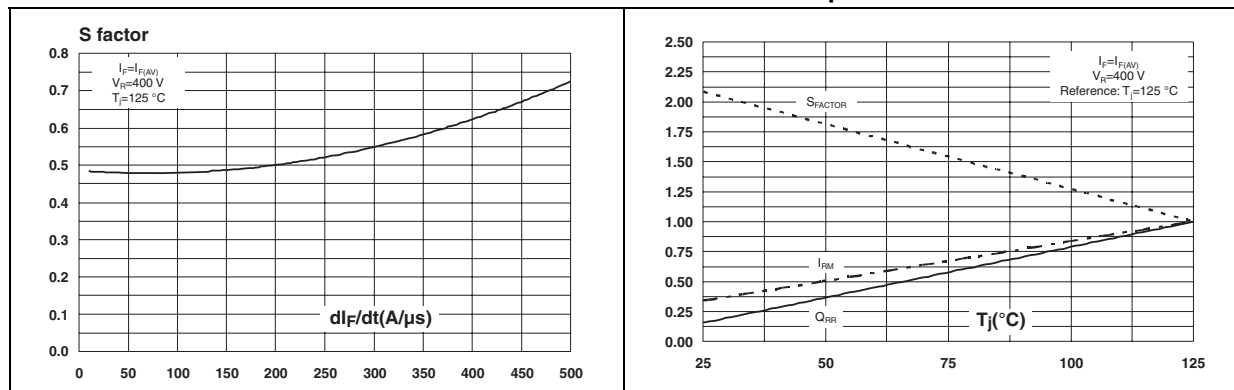


Figure 9. Transient peak forward voltage versus di_F/dt (typical values) **Figure 10. Forward recovery time versus di_F/dt (typical values)**

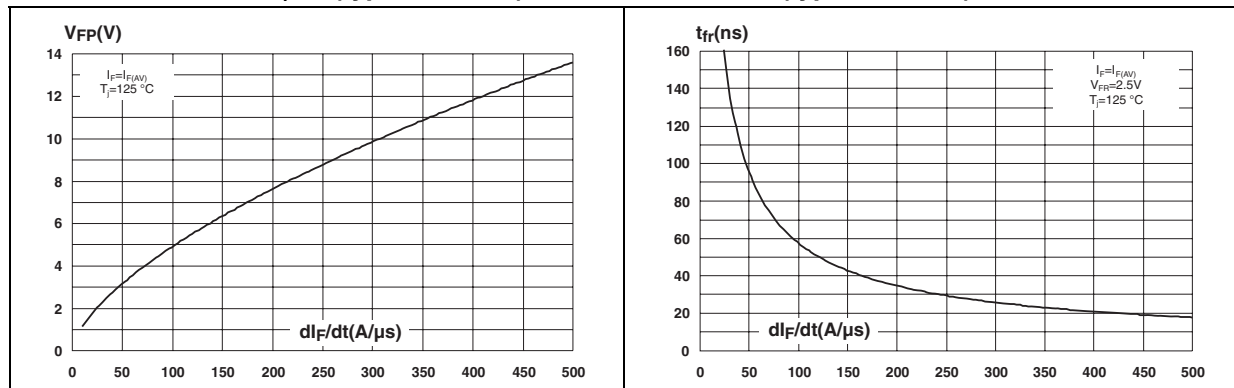


Figure 11. Junction capacitance versus reverse voltage applied (typical values)

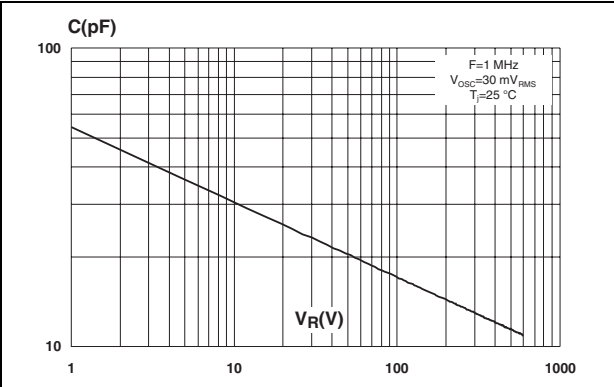


Figure 12. Thermal resistance junction to ambient versus copper surface under tab (D²PAK)

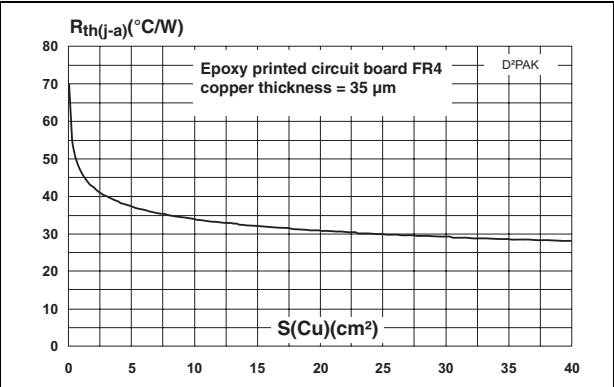
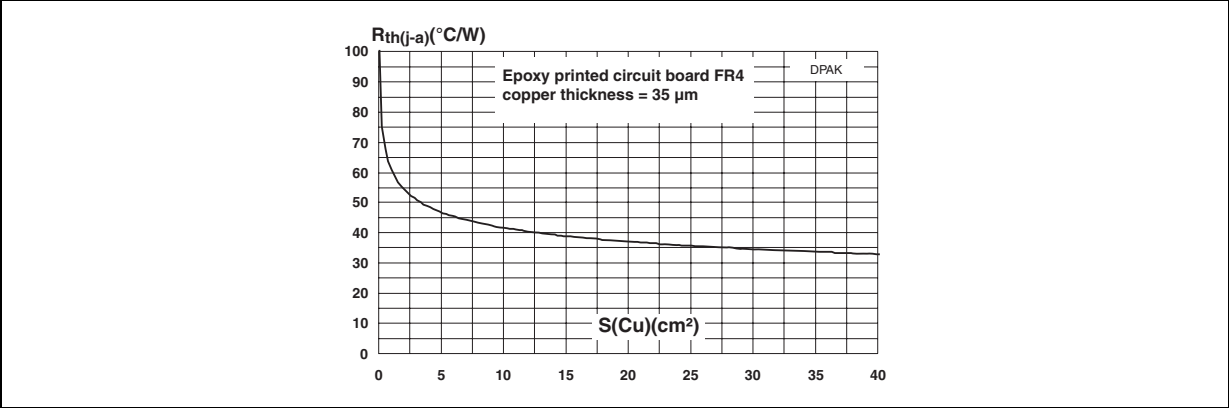


Figure 13. Thermal resistance junction to ambient versus copper surface under tab (DPAK)



- Epoxy meets UL94, V0
- Lead-free packages

Table 6. D²PAK dimensions

Figure 14. Footprint (dimensions in mm)

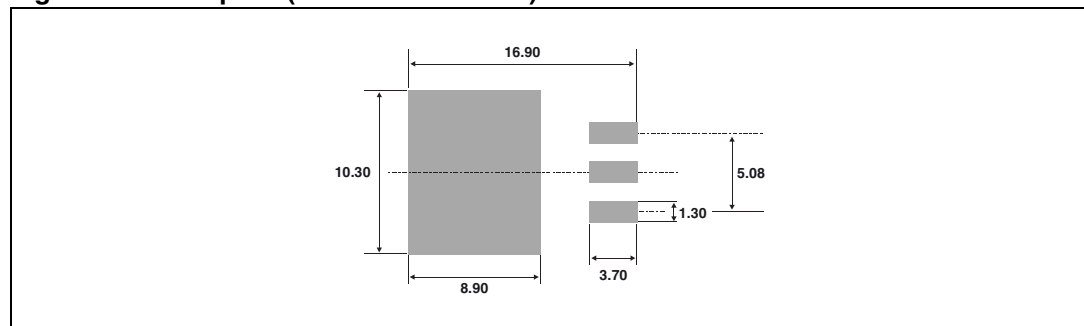
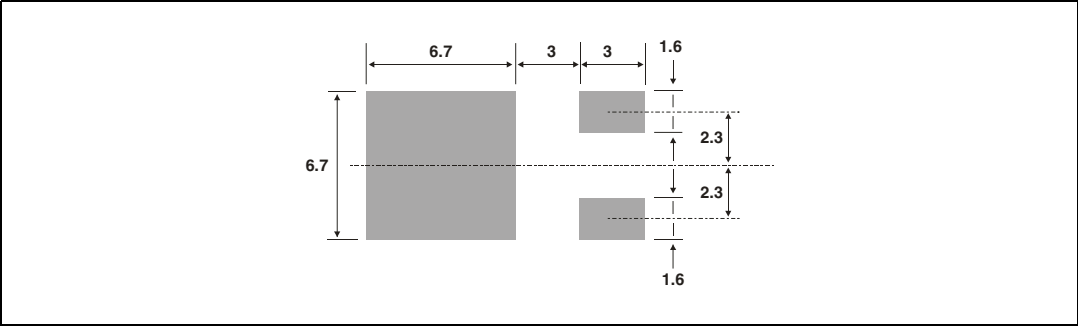


Table 7. DPAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 15. Footprint (dimensions in mm)



3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH5R06GY-TR	STTH5R06GY	D ² PAK	1.48 g	1000	Tape and reel
STTH5R06BY-TR	STTH5R06BY	DPAK	0.3 g	2500	Tape and reel

4 Revision history

Table 9. Document revision history

Date	Revision	Changes
03-Nov-2011	1	Initial release.

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